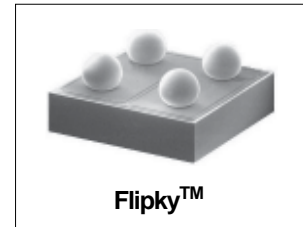


### Flipky™

1 Amp  
40 Volt

#### Features

- Ultra Low  $V_F$  per Footprint Area
- Low Leakage
- Low Thermal Resistance
- One-fifth Footprint of SMA
- Super Low Profile (<.7mm)
- Available Tested on Tape & Reel
- Lead-Free ("PbF" suffix)



#### Major Ratings and Characteristics

Characteristics	Values	Units
$I_{F(AV)}$ Rectangular waveform	1.0	A
$V_{RRM}$	40	V
$I_{FSM}$ @ $t_p = 5 \mu s$ sine	250	A
$V_F$ @ $1.0 A_{pk}, T_J = 125^\circ C$	0.42	V
$T_J$ range	-55 to 150	$^\circ C$

#### Description

True chip-scale packaging is available from International Rectifier. The IR1H40CSPTRPbF surface-mount Schottky rectifier has been designed for applications requiring low forward drop and very small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, free-wheeling diodes, battery charging, and reverse battery protection.

- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability

The Flipky™ package, is one-fifth the footprint of a comparable SMA package and has a profile of less than .7mm. Combined with the low thermal resistance of the die level device, this makes the Flipky™ the best device for application where printed circuit board space is at a premium and in extremely thin application environments such as battery packs, cell phones and PCMCIA cards.

## Voltage Ratings

Part number	IR1H40CSPTRPbF
$V_R$ Max. DC Reverse Voltage (V)	40
$V_{RWM}$ Max. Working Peak Reverse Voltage (V)	

## Absolute Maximum Ratings

Parameters	Value	Units	Conditions
$I_{F(AV)}$ Max. Average Forward Current	1.0	A	50% duty cycle @ $T_{PCB} = 117^\circ\text{C}$ , rectangular wave form
$I_{FSM}$ Max. Peak One Cycle Non-Repetitive Surge Current @ $25^\circ\text{C}$	250	A	5 $\mu\text{s}$ Sine or 3 $\mu\text{s}$ Rect. pulse
	21		10ms Sine or 6ms Rect. pulse
$E_{AS}$ Non-Repetitive Avalanche Energy	10	mJ	$T_J = 25^\circ\text{C}$ , $I_{AS} = 2.0\text{A}$ , $L = 5.0\text{mH}$
$I_{AR}$ Repetitive Avalanche Current	2.0	A	Current decaying linearly to zero in 1 $\mu\text{sec}$ Frequency limited by $T_J$ max. $V_a = 1.5 \times V_r$ typical

## Electrical Specifications

Parameters	Typ.	Max.	Units	Conditions	
$V_{FM}$ Max. Forward Voltage (1) Drop * See Fig. 1	0.48	0.52	V	@ 1A	$T_J = 25^\circ\text{C}$
	0.54	0.59		@ 2A	
	0.38	0.42		@ 1A	$T_J = 125^\circ\text{C}$
	0.48	0.52		@ 2A	
$I_{RM}$ Max. Reverse Leakage (1) Current * See Fig. 2	3	15	$\mu\text{A}$	$T_J = 25^\circ\text{C}$	$V_R = \text{rated } V_R$
	0.5	1			$V_R = 20\text{V}$
	0.2	0.5			$V_R = 10\text{V}$
	0.15	0.3			$V_R = 5\text{V}$
	2.5	4	mA	$T_J = 125^\circ\text{C}$	$V_R = \text{rated } V_R$
	0.9	2			$V_R = 20\text{V}$
	0.6	1.5			$V_R = 10\text{V}$
	0.5	1			$V_R = 5\text{V}$
$C_T$ Max. Junction Capacitance	-	160	pF	$V_R = 5V_{DC}$ (test signal range 100kHz to 1MHz) $25^\circ\text{C}$	
$dv/dt$ Max. Voltage Rate of Charge	-	10000	V/ $\mu\text{s}$	(Rated $V_R$ )	

(1) Pulse Width < 300 $\mu\text{s}$ , Duty Cycle < 2%

## Thermal-Mechanical Specifications

Parameters	Value	Units	Conditions
$T_J$ Max. Junction Temperature Range (*)	-55 to 150	$^\circ\text{C}$	
$T_{stg}$ Max. Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
$R_{thJL}$ Typ. Thermal Resistance Junction to PCB (**)	40	$^\circ\text{C}/\text{W}$	DCoperation
$R_{thJA}$ Max. Thermal Resistance Junction to Ambient	62	$^\circ\text{C}/\text{W}$	

(\*)  $dP_{tot} < \frac{1}{dT_j} \cdot R_{th(j-a)}$  thermal runaway condition for a diode on its own heatsink

(\*\*) Mounted 1 inch square PCB

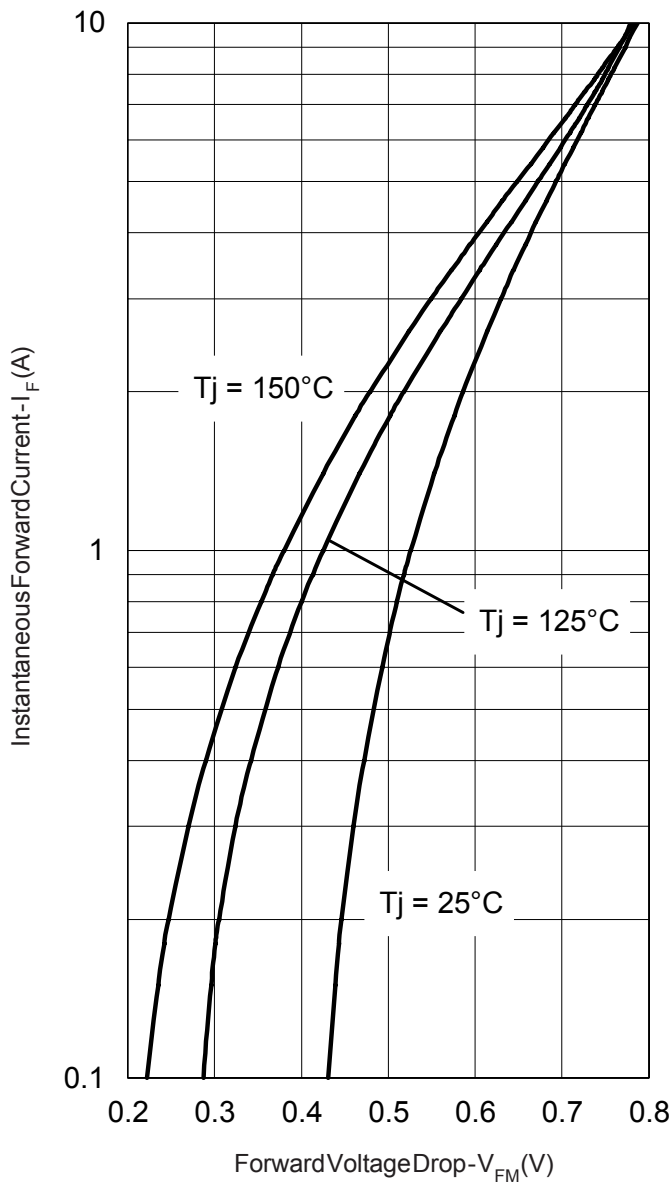


Fig. 1 - Max. Forward Voltage Drop Characteristics (Per Leg)

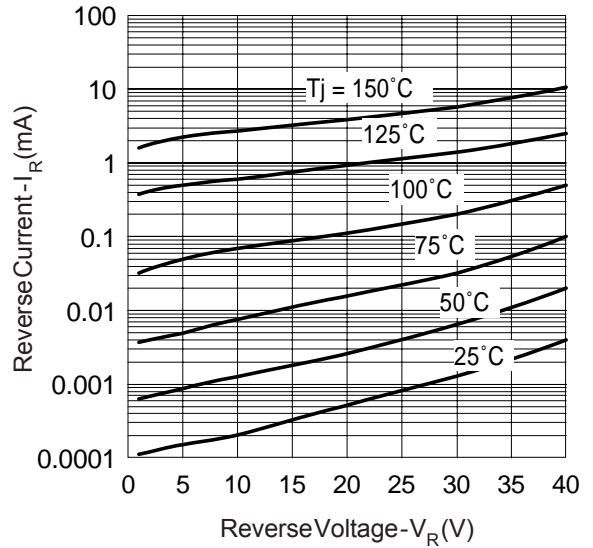


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage (Per Leg)

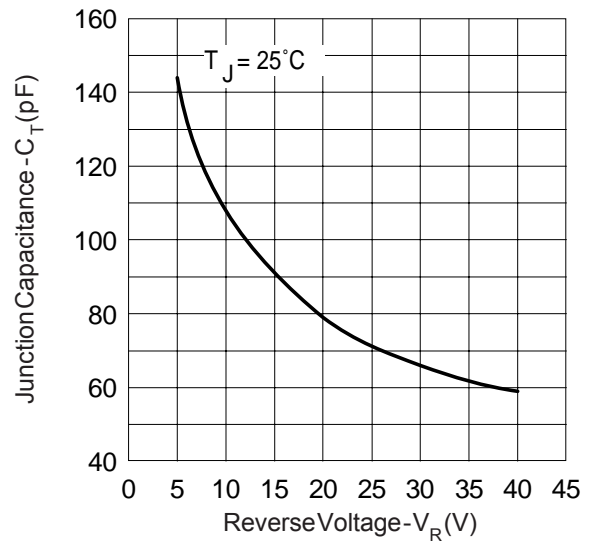


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage (Per Leg)

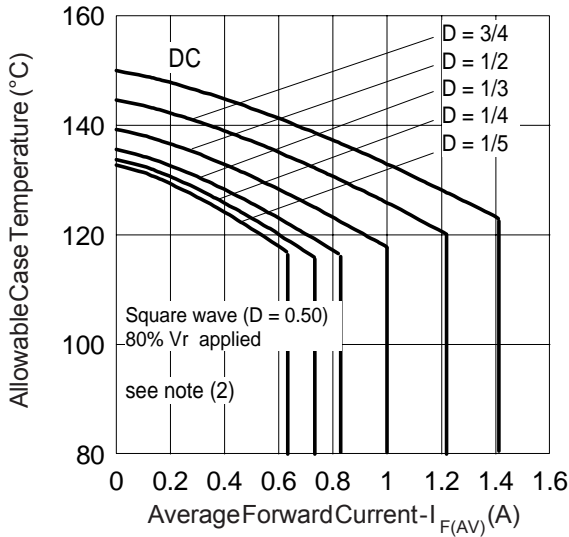


Fig.4-Max. Allowable Case Temperature Vs. Average Forward Current (PerLeg)

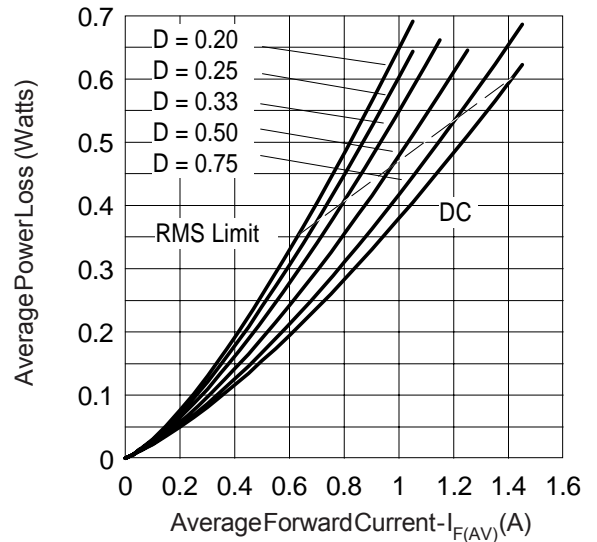


Fig.5-Forward Power Loss Characteristics (PerLeg)

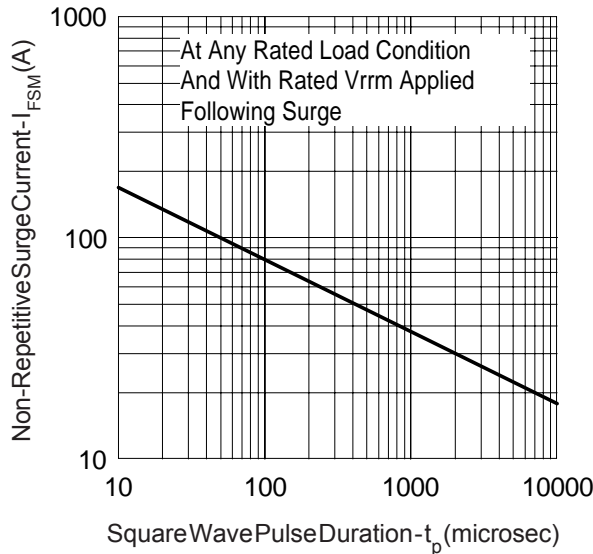


Fig.6-Max. Non-Repetitive Surge Current (PerLeg)

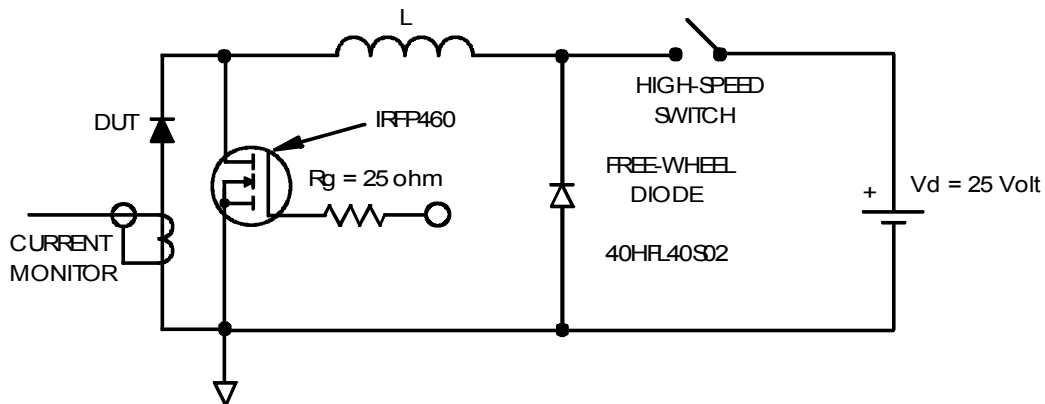
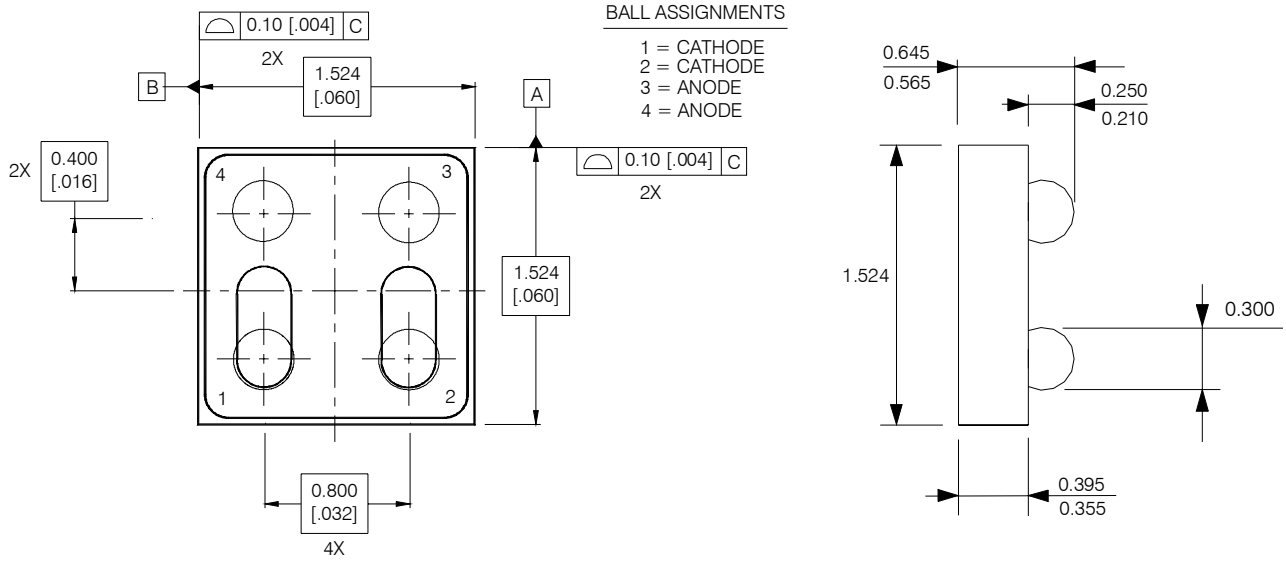


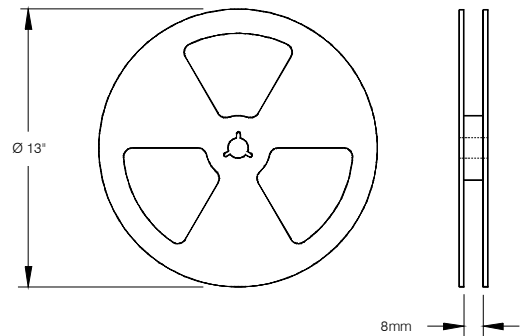
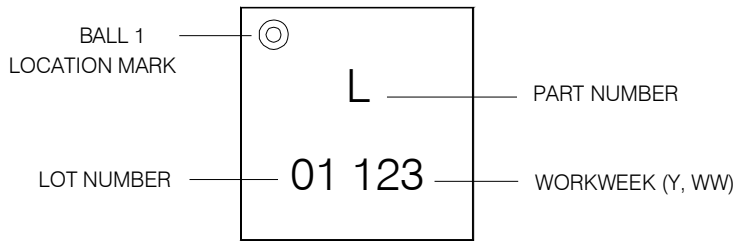
Fig.8-Unclamped Inductive Test Circuit

- (2) Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$  ;  
 $Pd = \text{Forward Power Loss} = I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$  (see Fig. 6);  
 $Pd_{REV} = \text{Inverse Power Loss} = V_{R1} \times I_R (1 - D)$ ;  $I_R @ 80\% V_R$  applied

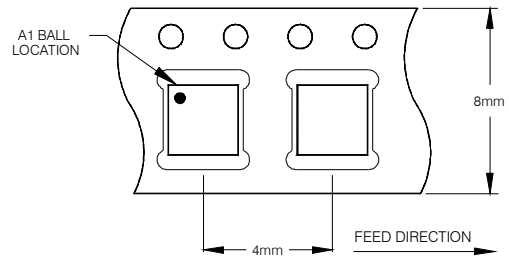
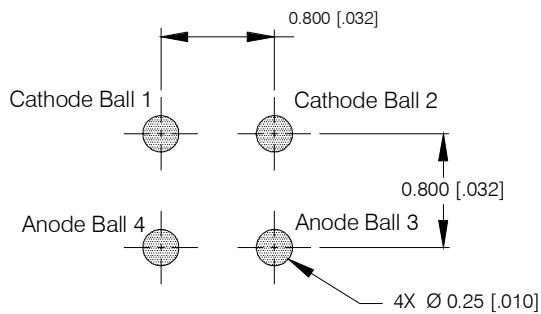
### FlipKY™ Outline Dimension and Tape and Reel



- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
  2. CONTROLLING DIMENSION: MILLIMETER
  3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].



#### RECOMMENDED FOOTPRINT



- NOTES:
1. TAPE AND REEL OUTLINE CONFORMS TO EIA-481 & EIA-541.

IR1H40CSP

\*\*\*\*\*

\* This model has been developed by \*

\* Wizard SPICE MODEL GENERATOR (1999) \*

\* (International Rectifier Corporation) \*

\* Contain Proprietary Information \*

\*\*\*\*\*

\* SPICE Model Diode is composed by a \*

\* simple diode plus paralalled VCG2T \*

\*\*\*\*\*

.SUBCKT irlh40csp ANO CAT

D1 ANO 1 DMOD (0.01614)

\*Define diode model

.MODEL DMOD D(IS=1.89451920631734E-05A,N=1.28115932154793,BV=48V,  
+ IBV=3.51582918628388E-02A,RS= 0.000316344,CJO=1.496133161627E-08,  
+ VJ=2.48275231672173,XTI=2, EG=0.909092986033443)

\*\*\*\*\*

\*Implementation of VCG2T

VX 1 2 DC 0V

R1 2 CAT TRES 1E-6

.MODEL TRES RES(R=1,TC1=141.418786575201)

GP1 ANO CAT VALUE={-ABS(I(VX))\*(EXP(((((-4.18234E-03/  
141.4188)\*(V(2,CAT)\*1E6)/(I(VX)+1E-6)-1))+1)\*0.1008349\*ABS(V(ANO,CAT)))-  
1)}

\*\*\*\*\*

.ENDS irlh40csp

Data and specifications subject to change without notice.  
This product has been designed and qualified for Consumer Level and Lead-Free.  
Qualification Standards can be found on IR's Web site.

International  
IOR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

TAC Fax: (310) 252-7309

05/06



## Notice

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